Supplementary Materials: Direct-Write Dewetting of High Melting Temperature Metals on Flexible Substrates

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Supplementary Information

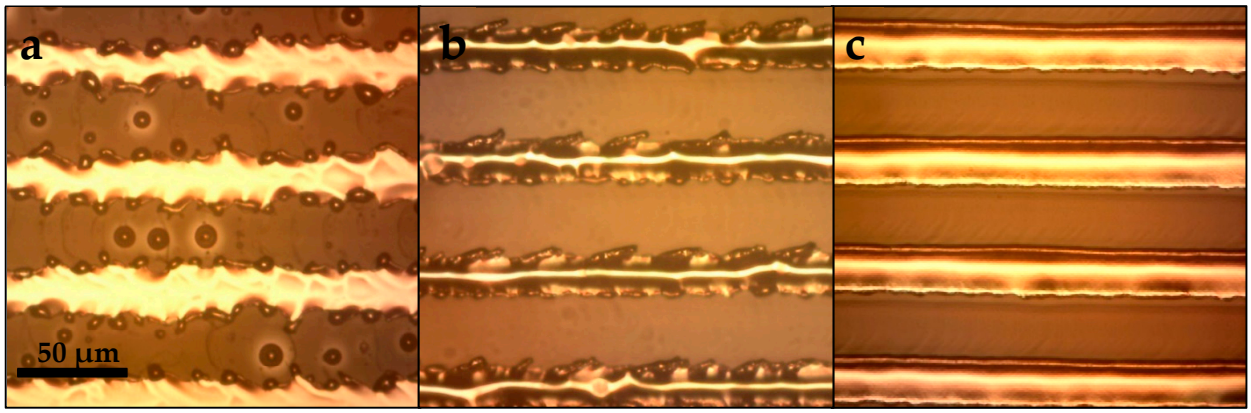

Figure S1: Ni films deposited to a thickness of (**a**) 320 nm on glass, (**b**) 320 nm on Par-C, and (**c**) 640 nm on Par-C. All lines processed using the laser at 10 W with 2.5 µs pulses at 100 kHz. Films on glass were scanned at 0.3 m/s while films on Par-C were scanned at 0.2 m/s. All features are created at a 50 µm line-to-line pitch.

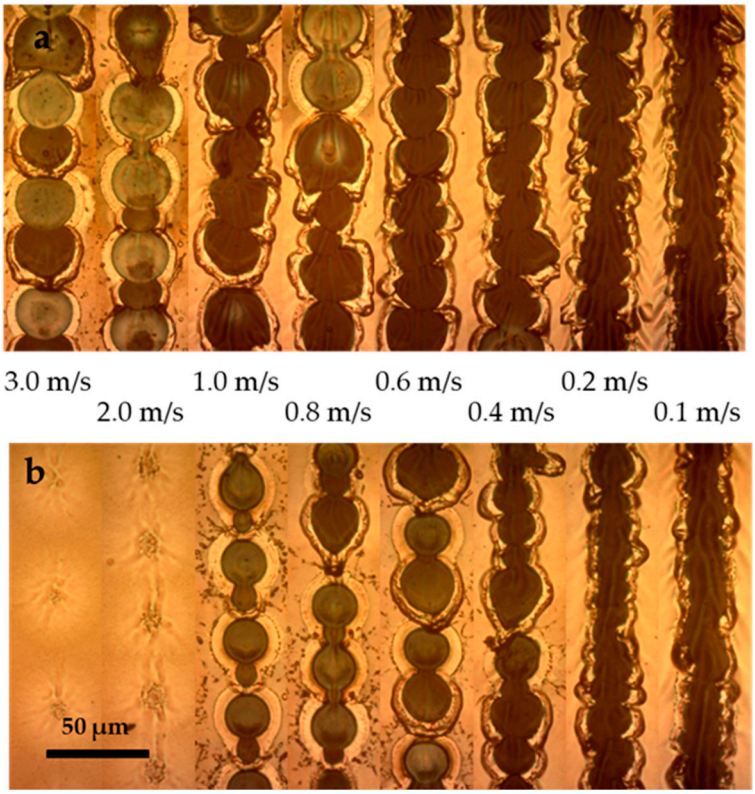

Figure S2: Bi-coated Ag films deposited on Par-C. Films were processed from the (**a**) "front" at 10 W where the Bi-film is directly exposed and from the (**b**) "back" at 40 W where the laser is routed through the glass and Par-C substrate to hit the Ag film directly bypassing the Bi film. Features are created using a 50 kHz, 5 µs regime and scanned at various speeds.

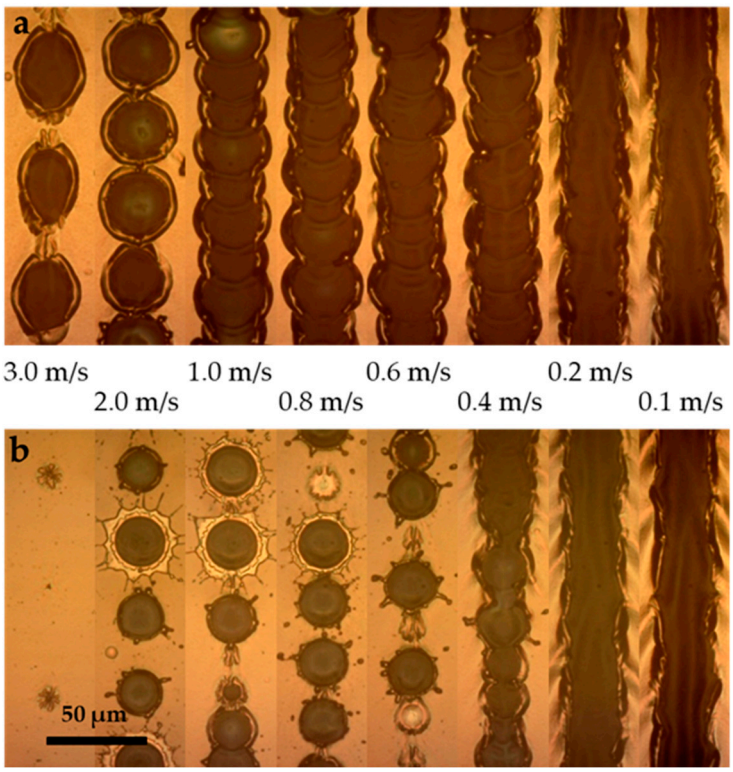

Figure S3. Ni-coated Ag films deposited on Par-C. Films were processed from the (**a**) "front" at 20 W where the Ni-film is directly exposed and from the (**b**) "back" at 40 W where the laser is routed through the glass and Par-C substrate to hit the Ag film directly bypassing the Ni film. Features are created using a 50 kHz, 5 µs regime and scanned at various speeds.